



PATENT
Atty. Dkt. No. AMAT/3778/CMP/CMP/RKK

PATENT

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Response

**Examiner:** Grant, A.

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TECHNOLOGY CENTER R3700

# CERTIFICATE OF MAILING

**37 CFR 1.8**

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6/13/02  
Date

Keith M. Tackett  
Keith M. Tackett

### IN THE CLAIMS:

1. (Amended) An apparatus, comprising a semiconductor polishing device having a first surface defining at least two non-intersecting fluid retaining grooves at least a portion of which is oriented at an angle relative to a radial line originating at a center of